

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6420988".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/23 22:26
L2	2	"6410988".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/23 22:31
L3	351071	ppm gpa	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/23 22:55
L4	17225	3 with ((thermal with (expansion coefficient)) (elastic modulus))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/23 22:57
L5	1324	(chip die flipchip (flip adj chip) semiconductor ic (integrated adj circuit)) with 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/23 22:58
L6	2707	(chip die flipchip (flip adj chip) semiconductor ic (integrated adj circuit)) same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/23 22:58
L7	1526	(substrate carrier board pcb wb) same 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/23 22:59
L8	821	(stiffener stud post lid cover) and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/23 23:03